

Product Name: ZX050C-DFN1010 (X1-DFN1010-4 X2-DFN1010-4) Characterization testing bringup breakout module

Product Description: High Speed characterization module meeting 10GHz signal bandwidth with < 0.3dB insertion loss. Each pin of the device under test, U1, is accessible via 2 dedicated SMA connectors for external stimulus as well as measurement purpose.

ZX050C-DFN1010 is designed for ASIC (IC) characterization, functional testing of X1-DFN1010-4 X2-DFN1010-4 packaged device. ZX50C-DFN1010 is designed with 50 Ω (Ohms) trace impedance using 4 layer PCB. The module includes 35μ gold plated SMA connectors.

Ideal evaluation, bringup, and testing of any discrete component such as ESD diode, sensor, or any IC using X1-DFN1010-4 , X2-DFN1010-4 footprint package.

Available Rxy to GND on each U1 pin (xy is the U1 pin number). Rxy is unpopulated 0402 SMD footprint. User may apply any standard 0402 device as required, resistor, capacitor, bead. . .

Available GND test point header pin interfacing with the module's GND plane & GND fills

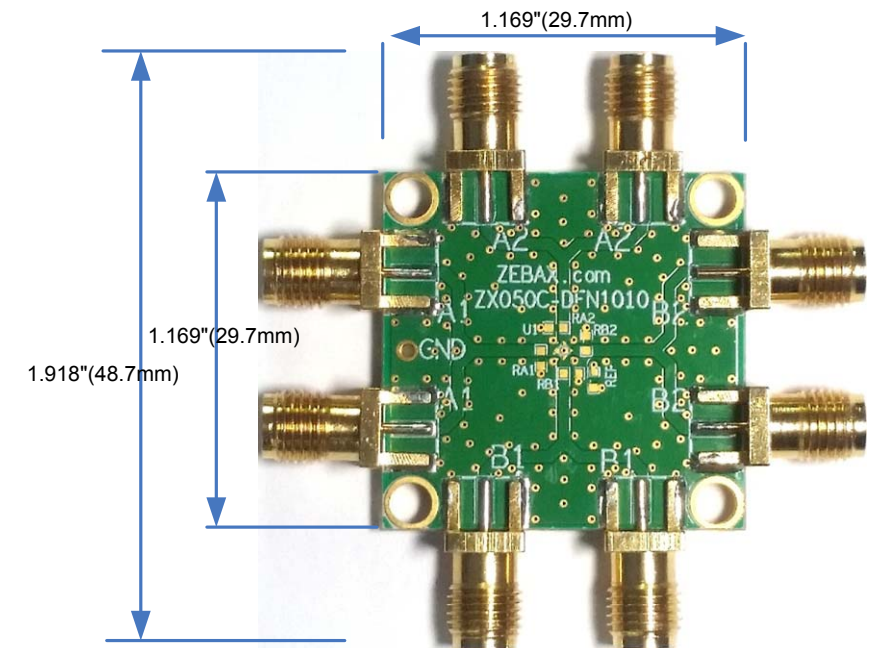
Application: Bringup, Characterization, testing, development, modular design evaluations

Target DUT : Designed specifically for any DFN1010-4 (X1-DFN1010-4 X2-DFN1010-4) SMD device with SMA connectors accessing all pins of the DFN1010-4

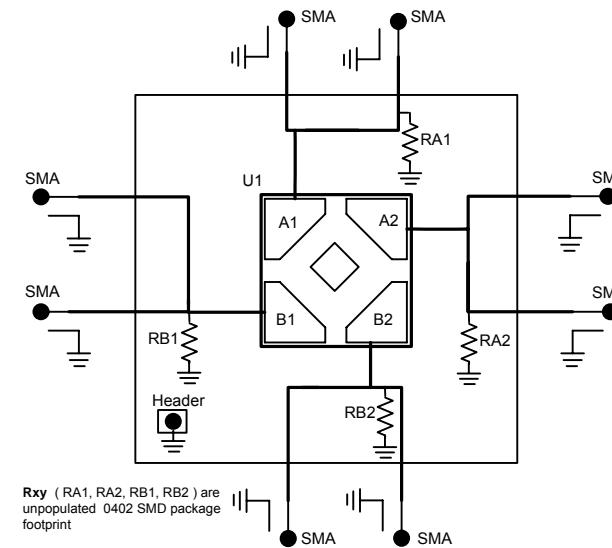
Pitch: Standard DFN1010-4 (X1-DFN1010 X2-DFN1010-4) SMD package or equivalent

Headers: Ground access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height

DUT landing pads: Surface Mount, 4 pin package – DFN1010-4 (X1-DFN1010-4 X2-DFN1010-4) or equivalent



Simplified Block Diagram:



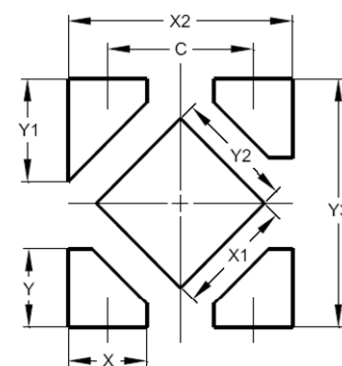
Rxy (RA1, RA2, RB1, RB2) are unpopulated 0402 SMD package footprint

DFN1010-4 DIMENTIONS (mm)

UNIT		c	X	Y	X1	Y1	X2	Y2	Y3
mm	max typical min	0.650	0.350	0.350	0.527	0.455	1.000	0.527	1.10

OUTLINE Version	REFERENCES		
	IEC	JEDEC	JEITA
X2-DFN1010-4			
X1-DFN1010-4			

Pad Layout



SMA:
 Impedance: 50Ω
 Temp Range: -65°C +165°C
 Vibration: MIL-STD-202, Method 213
 Frequency Range: DC – 12GHz
 Working Voltage: 335V max
 Withstand Voltage: 1000V rms
 Center Contact: ≤3mΩ
 Outer Contact: ≤2mΩ
 Insulation resistance: ≥5000MΩ
 VSWR Straight: ≤1.15 (0.8-2.5G)

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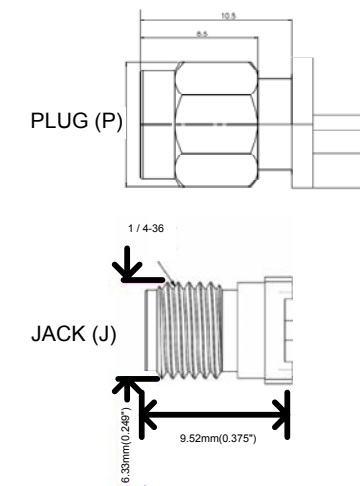
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Ordering INFO:

Part Number
 ZX050C-DFN1010J SMA Jack Connector type (standard)
 ZX050C-DFN1010P SMA Plug connector type

NOTE: ZX050C-DFN1010 is shipped without DUT. All SMA connectors are installed.

Note
 ALL ZEBAX products are RoHS compliant and Lead Free unless otherwise indicated.



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SPECIFIED DIMENSIONS ARE INCHES (MM). ROHS COMPLIANT	ASSEMBLY DRAWING	
	ITEM: ZX050C-DFN1010	
DESCRIPTION: DFN1010-4 (X1-DFN1010-4 X2-DFN1010-4) characterization testing bringup breakout adapter SMA		
CHECKED: M. MARINA	DRAWN: SLAVIK	REVISION: 1.0
		SHEET: 1 OF 1